

Applications

- HFC Nodes
- CATV Line Amplifiers
- Head End Equipment

Product Features

- Excellent High Output Linearity
- High Gain 24dB @ 1000MHz
- 50MHz – 1000MHz Bandwidth
- Ultra-Low CSO/CTB/XMOD
- Low Noise
- Excellent Input/Output Match
- Variable Bias Control
- Compact Size
- High Reliability
- 24V, 445mA

General Description

The TAT9988 is an ultra-linear, packaged GaAs/GaN amplifier intended for output stage amplification in CATV infrastructure applications.

The TAT9988 features a push-pull cascode design which provides flat gain along with ultra-low distortion, making it ideal for use in CATV distribution systems requiring high output power capability.

The TAT9988 draws 445mA from a 24V supply and exceeds the output linearity performance of traditional GaAs-based amplifiers.

The TAT9988 allows users to adjust the bias current and the bias voltage externally in order to optimize output performance.

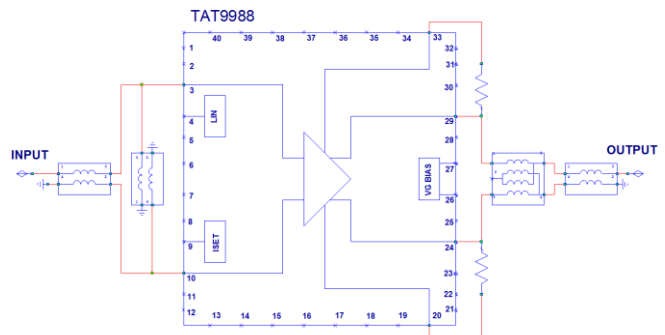
The TAT9988 is packaged in an industry standard 40 pin 5x7 mm² QFN package.

Standard SOT-115 Hybrid Modules are used as orderable evaluation board assemblies for the TAT9988. Please refer to the ordering information for more details.



40 Pin 5x7 mm QFN Package

Functional Block Diagram



Pin Configuration

| Pin No. | Label |
|-------------------------------------|--------------------------------|
| 3 | Non-Inverting Amplifier Input |
| 4 | Linearizer Current-Adjust |
| 6,7 | Common Source Node |
| 9 | Amplifier Current-Adjust |
| 10 | Inverting Amplifier Input |
| 20 | Feedback to Inverting Input |
| 24 | Non-Inverting Amplifier Output |
| 26 | Output Device Gate Bias 1 |
| 27 | Output Device Gate Bias 2 |
| 29 | Inverting Amplifier Output |
| 33 | Feedback to Non-Inverting |
| 1,2,5,8,11-12, 21-23,25, 28, 30-32, | No connect |
| 13-19, 34-40 | Ground |

Ordering Information

| Part No. | Description |
|--------------|-------------------------------------|
| TAT9988 | CATV GaN Power Doubler MMIC |
| TAT8888 | 50-1000 MHz Hybrid Evaluation Board |
| TAT8888-1200 | 50-1200 MHz Hybrid Evaluation Board |

Standard T/R size =1000 pieces on a 7" reel.

Absolute Maximum Ratings

| Parameter | Rating |
|-----------------------------------|---------------|
| Storage Temperature | -40 to +100°C |
| RF Input Power, CW, 75Ω, T=25°C | 70 dBmV |
| Supply Voltage (V _{DD}) | +30 V |
| Supply Current (I _{DD}) | 600 mA |

Operation of this device outside the parameter ranges given above may cause permanent damage.

Recommended Operating Conditions

| Parameter | Min | Typ | Max | Units |
|--------------------------------------|-----|-----|------|-------|
| Supply Voltage (V _{DD}) | | 24 | | V |
| Case Temperature | -30 | | +100 | °C |
| Junction Temperature, T _j | | | 155 | °C |

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Typical Performance – Push-Pull Configuration ⁽¹⁾

Test conditions unless otherwise noted: V_{DD}=+24 V, 75 Ω System, Base Temp=+35°C.

| Parameter | Conditions | Min | Typ | Max | Units |
|-------------------------------------|--------------------------------------------------------------------|------|------|-------|-------|
| Operating Frequency | | 50 | | 1000 | MHz |
| Gain | Tested at 1000 MHz | 23 | 23.5 | 24.25 | dB |
| Gain Slope | 45 to 1003 MHz | 0.25 | | 1.5 | dB |
| Gain Flatness | Relative to Slope Line | | ±0.5 | ±0.8 | dB |
| Input Return Loss ⁽²⁾ | | | 18 | | dB |
| Output Return Loss ⁽²⁾ | | | 19 | | dB |
| CSO | | | -69 | -65 | dBc |
| CTB | 79 channels NTSC | | -75 | -69 | dBc |
| XMOD | 75 channels QAM, -6dB offset, 60 dBmV virtual output, 18dB Tilt | | -65 | | dBc |
| CCN | | 55 | 59 | | dBm |
| Output IP3 | P _{out} = 19 dBm/tone, at 500 MHz Δf = 6 MHz | | 53 | | dB |
| Noise Figure | | | 3.5 | | dB |
| Supply Current, I _{DD} | | 410 | 445 | 470 | mA |
| Thermal Resistance, θ _{jc} | Junction to case | | 5 | | °C/W |

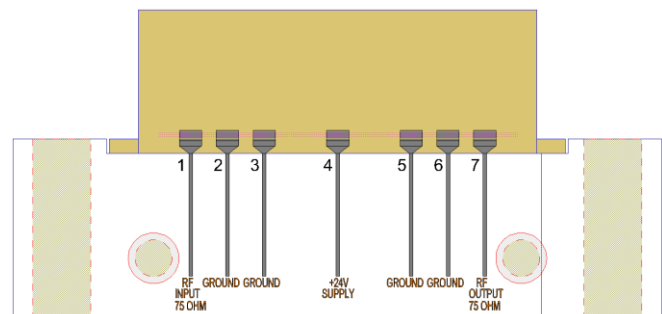
Notes:

1. Includes balun, board, and connector losses.
2. Return losses dependent on balun and transformer selection.

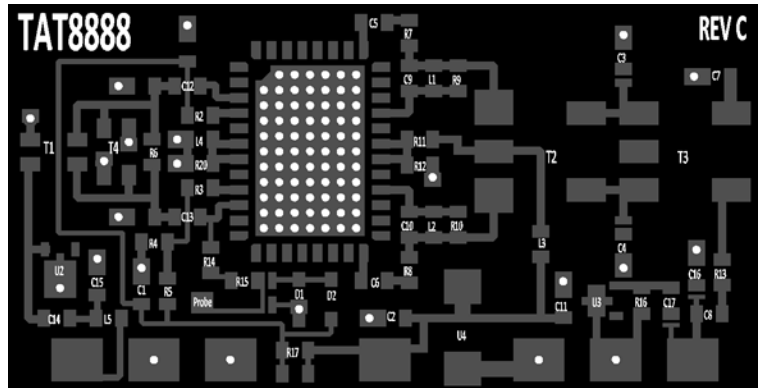
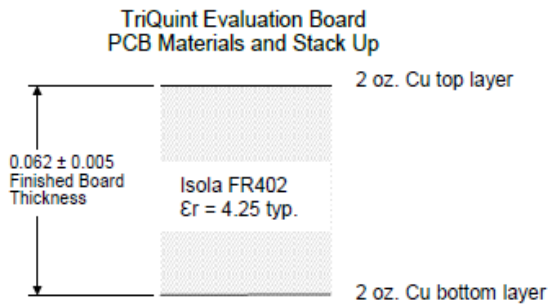
EVB Information – TAT8888 Hybrid Evaluation Board Assembly



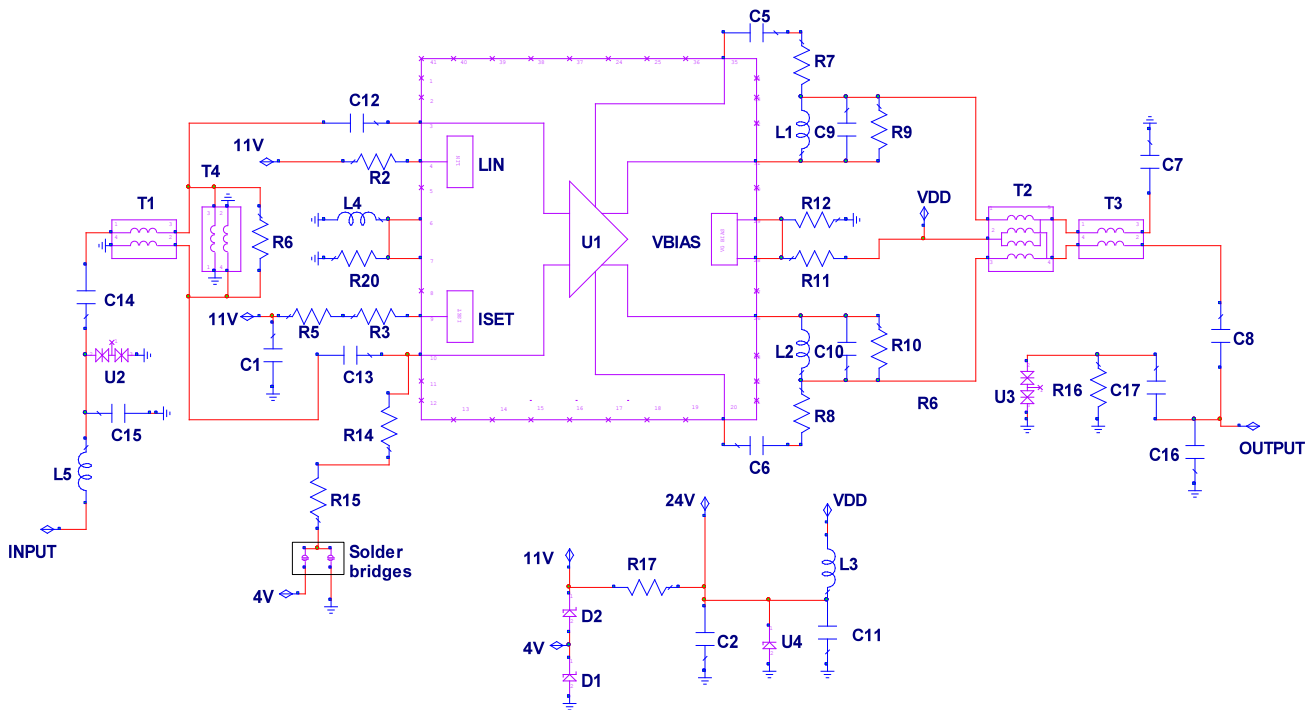
SOT-115 Hybrid Module



EVB Information – TAT8888 Hybrid Evaluation Board PCB



Application Schematic – TAT8888 Hybrid Evaluation Board



Notes:

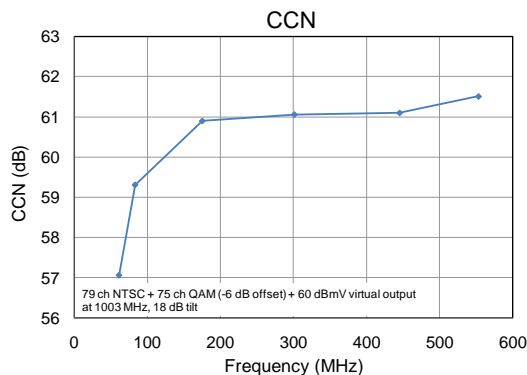
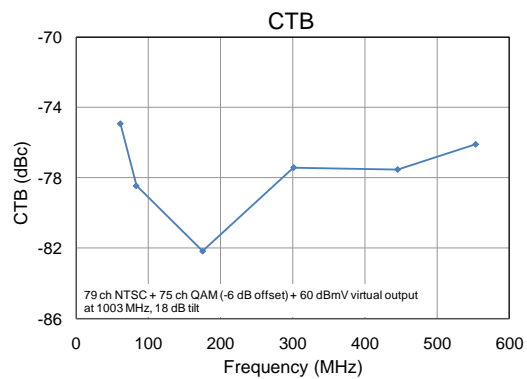
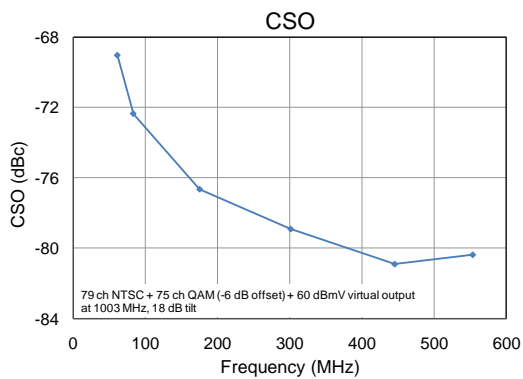
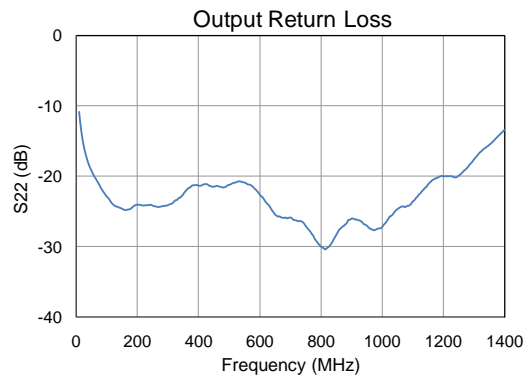
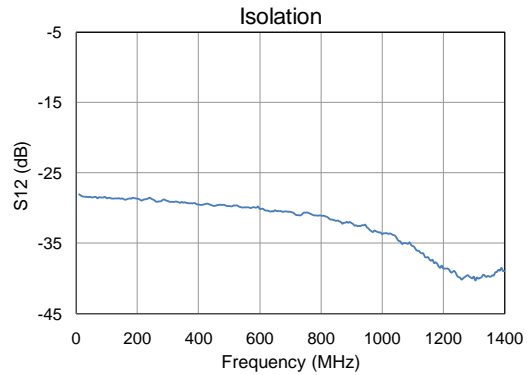
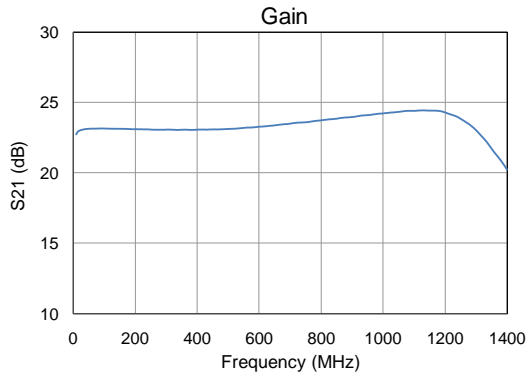
1. See Evaluation Board PCB Information section for PCB material and stack-up.
2. Components are 0402 unless specified otherwise.

Bill of Material – TAT8888 Hybrid Evaluation Board

| Reference Des. | Value | Description | Manuf. | Part Number |
|---------------------------------------|---------|-------------------------------------|--------------------|------------------------|
| U1 | | CATV GaN Power Doubler Module | TriQuint | TAT9988 |
| C1, C2, C5, C6, C7, C8, C11, C14, C17 | 0.01 uF | Cap, Chip, 0402, X7R, 50V, 10% | Various | |
| C9, C10, C16 | 0.5 pF | Cap, Chip, 0402, COG, 50V, ± 0.1 pF | Various | |
| C12, C13 | 270 pF | Cap, Chip, 0402, NPO, 50V, 5% | Various | |
| C15 | 0.3 pF | Cap, Chip, 0402, COG, 50V, ± 0.1 pF | Various | |
| L1, L2 | 9.1 nH | Ind, Chip, 0402, 540mA, 5.5GHz, 5% | Murata | LQP15AN9N1J00D |
| L3, L4 | 220 Ω | Bead, Chip, 0402, 700mA, 25% | Murata | BLM15EG221SN1D |
| L5 | 0 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R2, R12 | 2.40 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R3 | 1.60 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R5 | 390 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R6, R7, R8 | 1.10 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R9, R10 | 750 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R11, R14, R16 | 15.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R13 | 0 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R15 | 10.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R17 | 2.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R20 | 10.0 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| T1, T4 | 1:1 | Balun | Murata | DXW21BN7511SL |
| T2 | 2.6:1 | Transformer | Mintronix | MRF20003 |
| T3 | 1:1 | Balun | Mintronix or MACOM | MRF20001 MABACT0059 |
| U2, U3 | N/A | ESD protection , IC | TriQuint | TQP200002 |
| U4 | 28V | Transient Suppressor, 28V, SOD123W | NXP | PTVS28VS1UR |
| D1 | 4.7V | Zener Diode, 4.7V, 2%, SOD523 | OnSemi | MM5Z4V7ST1G |
| D2 | 6.2V | Zener diode, 6.2V, 2%, SOD523 | OnSemi | MM5Z6V2ST1G |

Performance Plots – TAT8888 Hybrid Evaluation Board

Test conditions unless otherwise noted: $V_{DD}=+24$ V, 75 Ω System, Base Temp= $+35^{\circ}$ C.

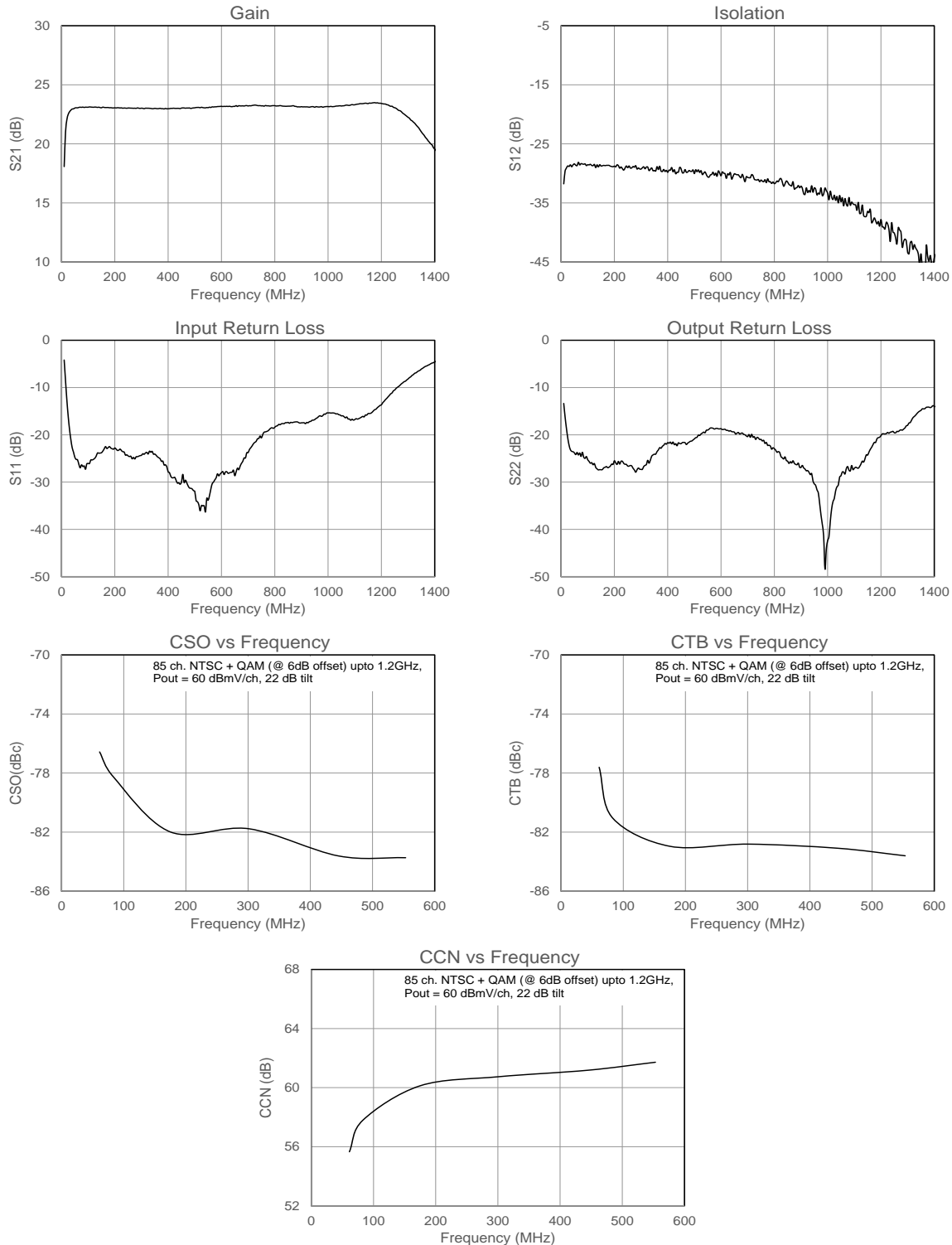


Bill of Material – TAT8888-1200 (50-1200 MHz Hybrid Evaluation Board)

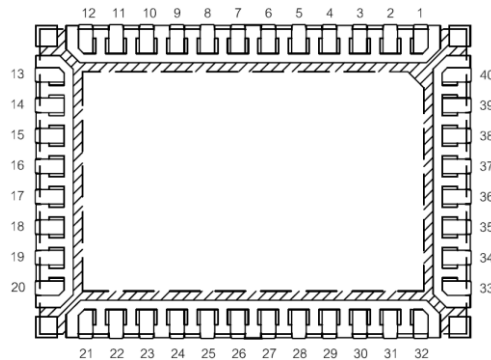
| Reference Des. | Value | Description | Manuf. | Part Number |
|---------------------------------------|---------|-------------------------------------|--------------------|------------------------|
| U1 | | CATV GaN Power Doubler Module | TriQuint | TAT9988 |
| C1, C2, C5, C6, C7, C8, C11, C14, C17 | 0.01 uF | Cap, Chip, 0402, X7R, 50V, 10% | Various | |
| C9, C10 | 0.2 pF | Cap, Chip, 0402, COG, 50V, ± 0.1 pF | Various | |
| C16 | 0.5 pF | Cap, Chip, 0402, COG, 50V, ± 0.1 pF | Various | |
| C12, C13 | 270 pF | Cap, Chip, 0402, NPO, 50V, 5% | Various | |
| C15 | 0.5 pF | Cap, Chip, 0402, COG, 50V, ± 0.1 pF | Various | |
| L1, L2 | 9.1 nH | Ind, Chip, 0402, 540mA, 5.5GHz, 5% | Murata | LQP15AN9N1J00D |
| L3, L4 | 220 Ω | Bead, Chip, 0402, 700mA, 25% | Murata | BLM15EG221SN1D |
| L5 | 8.2 nH | Ind, Chip, 0402, 540mA, 5.5GHz, 5% | Murata | LQP15AN8N2J00D |
| R2, R12 | 2.40 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R3 | 1.60 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R5 | 390 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R6, R7, R8 | 1.10 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R9, R10 | 750 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R11, R14, R16 | 15.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R13 | 0 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| R15 | 10.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R17 | 2.0 kΩ | Res, Chip, 0402, 0.1W, 1% | Various | |
| R20 | 10.0 Ω | Res, Chip, 0402, 0.1W, 1% | Various | |
| T1, T4 | 1:1 | Balun | Murata | DXW21BN7511SL |
| T2 | 2.6:1 | Transformer | Mintronix | MRF20003 |
| T3 | 1:1 | Balun | Mintronix or MACOM | MRF20001 MABACT0059 |
| U2, U3 | N/A | ESD protection , IC | TriQuint | TQP200002 |
| U4 | 28V | Transient Suppressor, 28V, SOD123W | NXP | PTVS28VS1UR |
| D1 | 4.7V | Zener Diode, 4.7V, 2%, SOD523 | OnSemi | MM5Z4V7ST1G |
| D2 | 6.2V | Zener diode, 6.2V, 2%, SOD523 | OnSemi | MM5Z6V2ST1G |

Performance Plots – TAT8888-1200 (50-1200 MHz Hybrid Evaluation Board)

Test conditions unless otherwise noted: $V_{DD}=+24$ V, 75 Ω System, Base Temp= $+35^{\circ}\text{C}$.



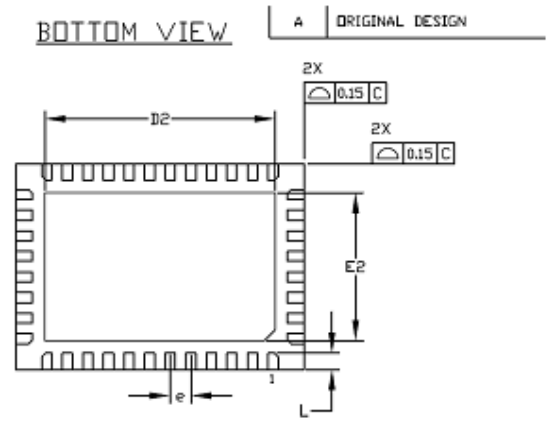
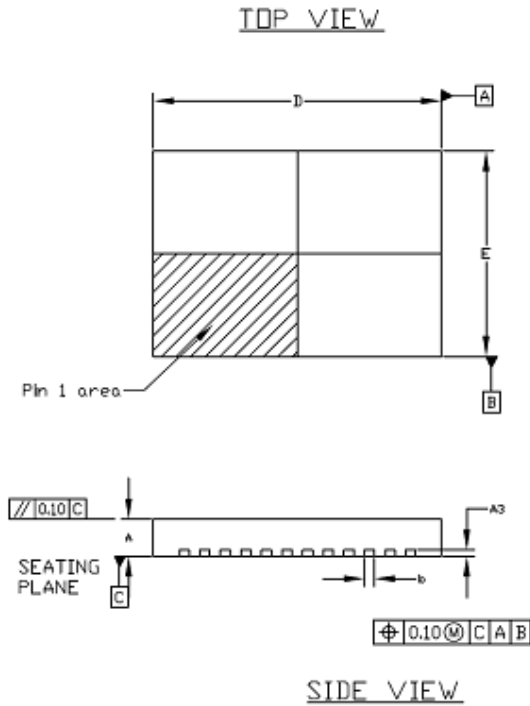
Pin Configuration and Description



| Pin No. | Function | Description |
|-----------------|---------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 3 | Non-Inverting Amplifier Input | Requires AC coupling from input balun |
| 4 | Linearizer Current-Adjust | Connect to VDD through resistors R4 and R8 |
| 6,7 | Common Source Node | DC GND. DC resistance to be minimized from this node to GND. |
| 9 | Amplifier Current-Adjust | Connect to VDD through resistor R3. |
| 10 | Inverting Amplifier Input | Requires AC coupling from input balun |
| 20 | Feedback to Inverting Input | Connects to non-inverting output (Pin 24). Path is layout sensitive and should be kept as short as possible. |
| 24 | Non-Inverting Amplifier Output | RF choke required to VDD through output transformer center tap. |
| 26 | Output Device Gate Bias 1 | Set to 3.25V using resistive divider network between VDD and GND. |
| 27 | Output Device Gate Bias 2 | Set to 3.25V using resistive divider network between VDD and GND. |
| 29 | Inverting Amplifier Output | RF choke required to VDD through output transformer center tap. |
| 33 | Feedback to Non-Inverting Input | Connects to inverting output (Pin 29). Path is layout sensitive and should be kept as short as possible. |
| Backside Paddle | RF/DC GND | Very low DC, RF and thermal resistance required from this node to the heatsink. Recommended via pattern should be followed to minimize thermal resistance. |

Package Marking and Dimensions

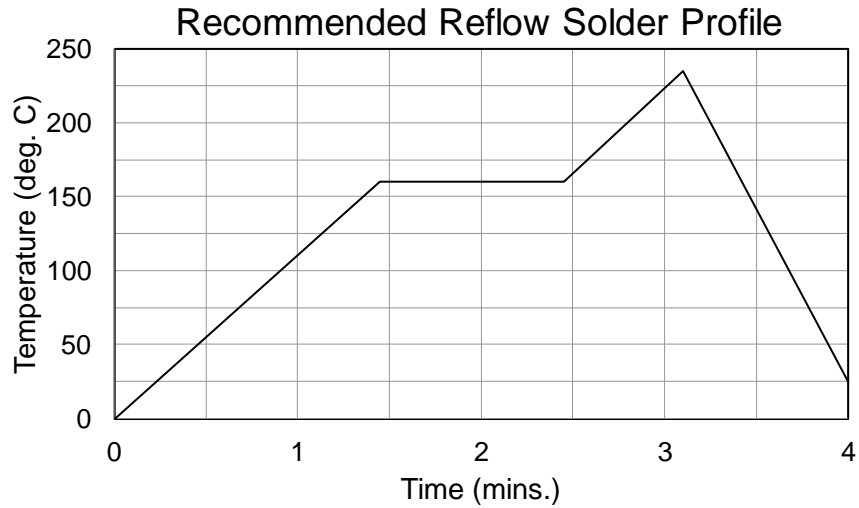
- Marking: Line 1: TriQuint Logo –
 Line 2: TAT9988 = Product code
 Line 3: YYWW CCCC = Date code, country code
 Line 4: AaXXXX = Aa = vendor code, Lot #



| SYMBOL | COMMON | | | | | |
|--------|-----------------------|------|------|-----------------|-------|-------|
| | DIMENSIONS MILLIMETER | | | DIMENSIONS INCH | | |
| | MIN. | NOM. | MAX. | MIN. | NOM. | MAX. |
| A | 0.85 | 0.90 | 0.95 | 0.034 | 0.036 | 0.038 |
| A3 | 0.203 REF | | | 0.008 REF | | |
| b | 0.20 | 0.25 | 0.30 | 0.008 | 0.010 | 0.012 |
| D | 6.85 | 7.00 | 7.15 | 0.269 | 0.275 | 0.281 |
| D2 | 5.50 | 5.60 | 5.70 | 0.216 | 0.220 | 0.224 |
| E | 4.85 | 5.00 | 5.15 | 0.190 | 0.196 | 0.202 |
| E2 | 3.50 | 3.60 | 3.70 | 0.137 | 0.141 | 0.145 |
| e | 0.50 REF | | | 0.020 REF | | |
| L | 0.30 | 0.40 | 0.50 | 0.012 | 0.016 | 0.020 |

Recommended Reflow Solder Profile

The following solder reflow profile is for a typical SAC305 no-lead solder paste application and assumes that industry standard PCB layout rules have been followed. Solder paste manufacturers will recommend a "typical" solder reflow profile depending on their particular solder paste's flux and metal composition. PCB size & composition, component density & position and reflow equipment are some of the factors that will impact and dictate the optimum reflow profile in specific manufacturing scenarios.



Product Compliance Information

ESD Sensitivity Ratings



Caution! ESD-Sensitive Device

ESD Rating: Class 0
Value: <250 Volts
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-C101

ESD Rating: Class III
Value: 500 to 1000 Volts
Test: Charged Device Model (CDM)
Standard: JEDEC Standard JESD22-C101

MSL Rating

MSL Rating: Level 3
Test: 260°C convection reflow
Standard: JEDEC Standard IPC/JEDEC J-STD-020

Solderability

Compatible with both lead-free (260°C maximum reflow temperature) and tin/lead (245°C maximum reflow temperature) soldering processes.

Contact plating: NiPdAu

RoHs Compliance

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free

Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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For technical questions and application information: Email: sjapplications.engineering@tqs.com

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